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(12) **United States Design Patent**
Leifeste et al.

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(54) **HANDHELD SEMICONDUCTOR WAFER HANDLING TOOL**

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(73) Assignee: **Raytheon Company**, Waltham, MA (US)

(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**; D8/14

(58) **Field of Classification Search**
USPC D8/14, 51, 107; D13/182
CPC H01L 21/67742; H01L 21/68707; B25J 15/0014
See application file for complete search history.

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Primary Examiner — Philip S Hyder

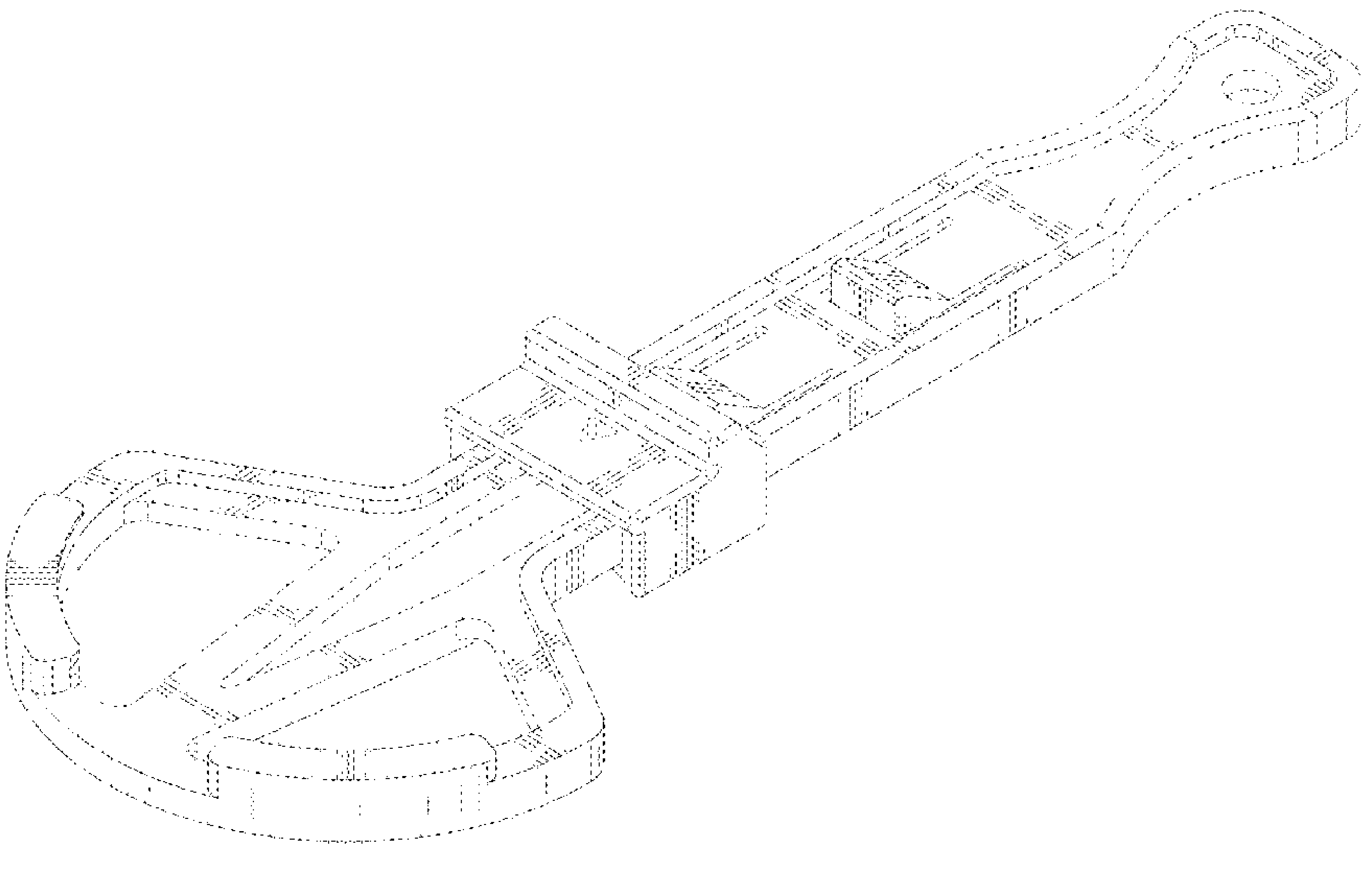
(57) **CLAIM**

The ornamental design for a handheld semiconductor wafer handling tool, as shown and described.

DESCRIPTION

FIG. **1** is a top front perspective view of a handheld semiconductor wafer handling tool with a movable clip in a first position;
FIG. **2** is a front end view of the handheld semiconductor wafer handling tool of FIG. **1**;
FIG. **3** is a back end view of the handheld semiconductor wafer handling tool of FIG. **1**;
FIG. **4** is a right side view of the handheld semiconductor wafer handling tool of FIG. **1**;
FIG. **5** is a left side view of the handheld semiconductor wafer handling tool of FIG. **1**;
FIG. **6** is a top view of the handheld semiconductor wafer handling tool of FIG. **1**;
FIG. **7** is a bottom view of the handheld semiconductor wafer handling tool of FIG. **1**;
FIG. **8** is a bottom rear perspective view of the handheld semiconductor wafer handling tool of FIG. **1**;
FIG. **9** is a top front perspective view of the handheld semiconductor wafer handling tool of FIG. **1** with the movable clip in a second position; and,
FIG. **10** is a perspective view of the handheld semiconductor wafer handling tool of FIG. **1** with a semiconductor wafer.
The broken line portions of the semiconductor wafer handling tool in FIGS. **1** through **10** are not considered part of the claimed design. Additional broken lines in FIG. **10** are provided for purposes of environment and form no part of the claimed design.

1 Claim, 8 Drawing Sheets



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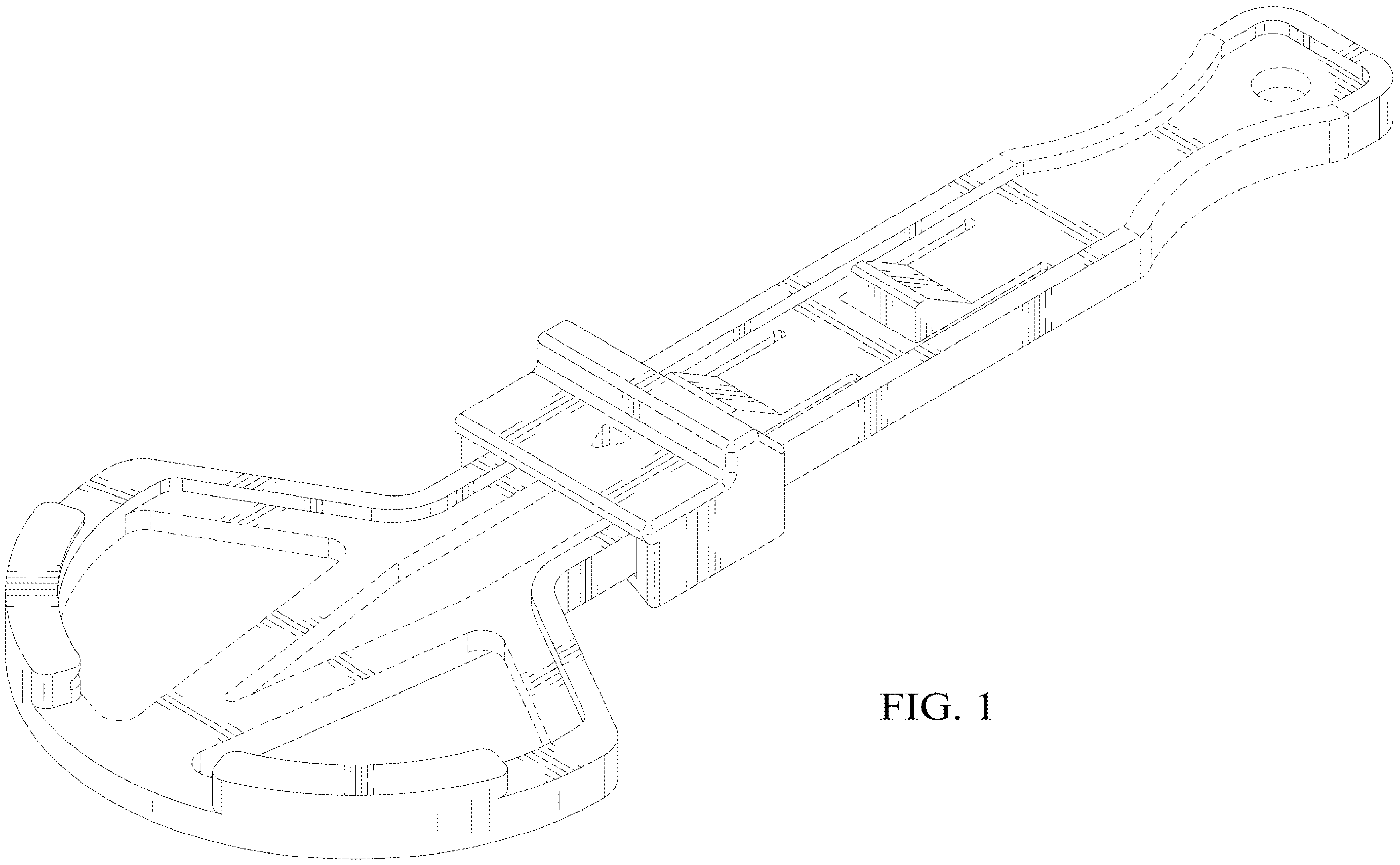

FIG. 1

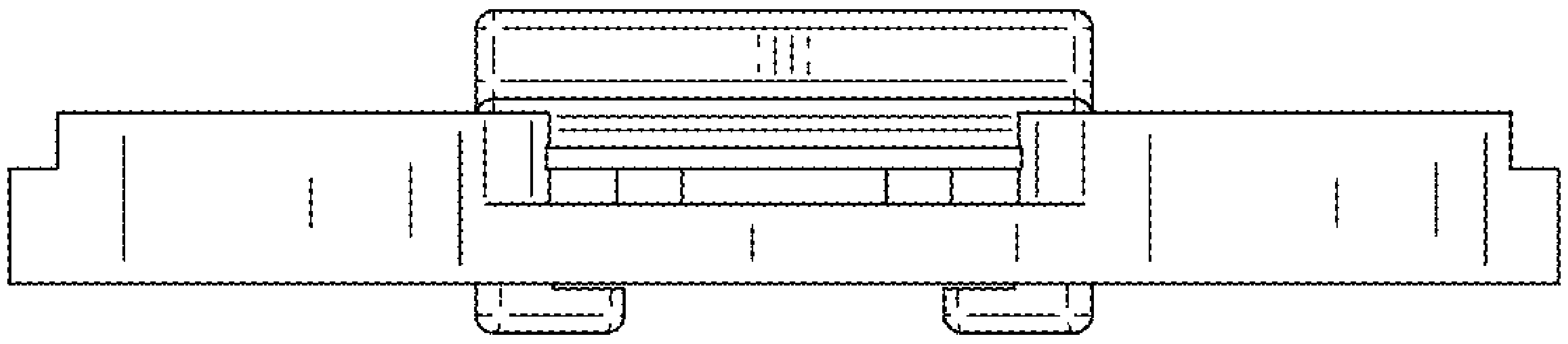

FIG. 2

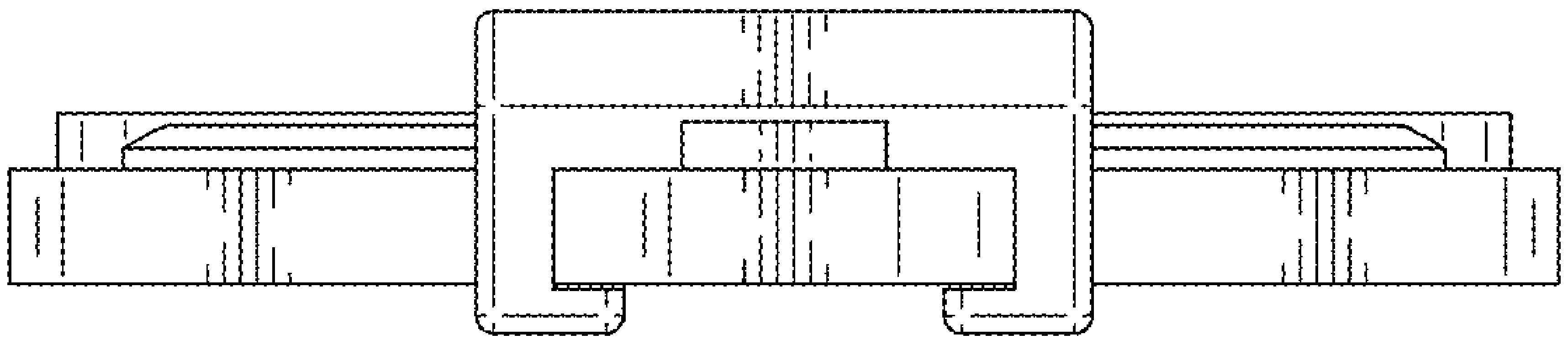

FIG. 3

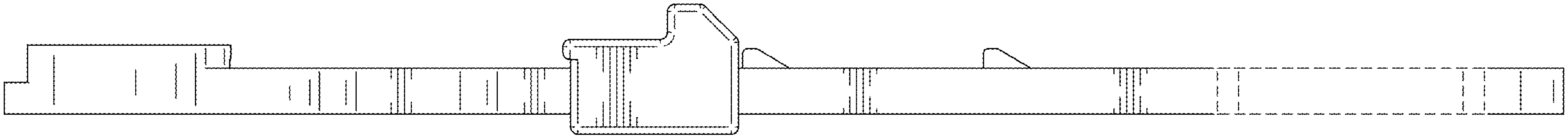

FIG. 4

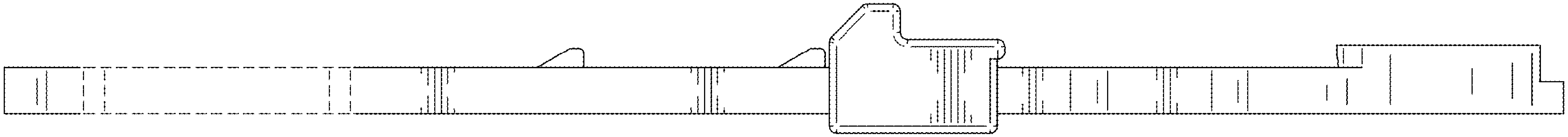

FIG. 5

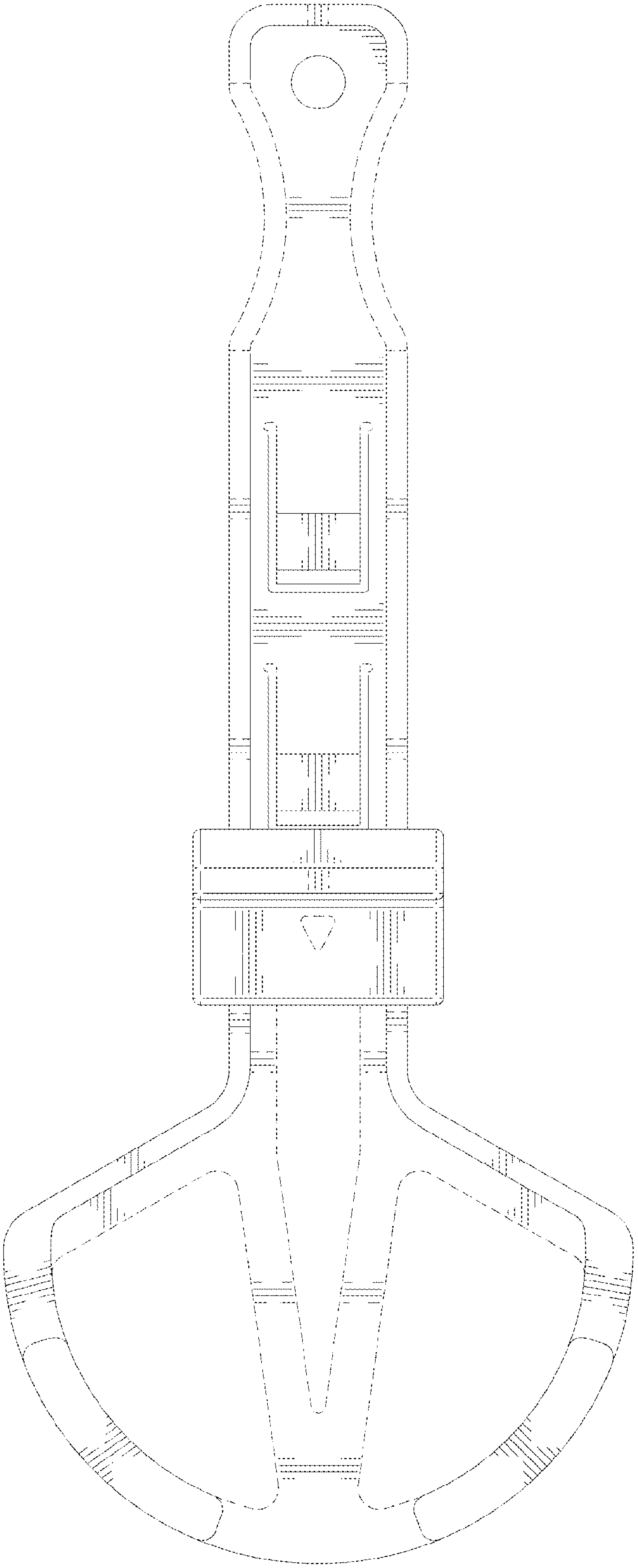

FIG. 6

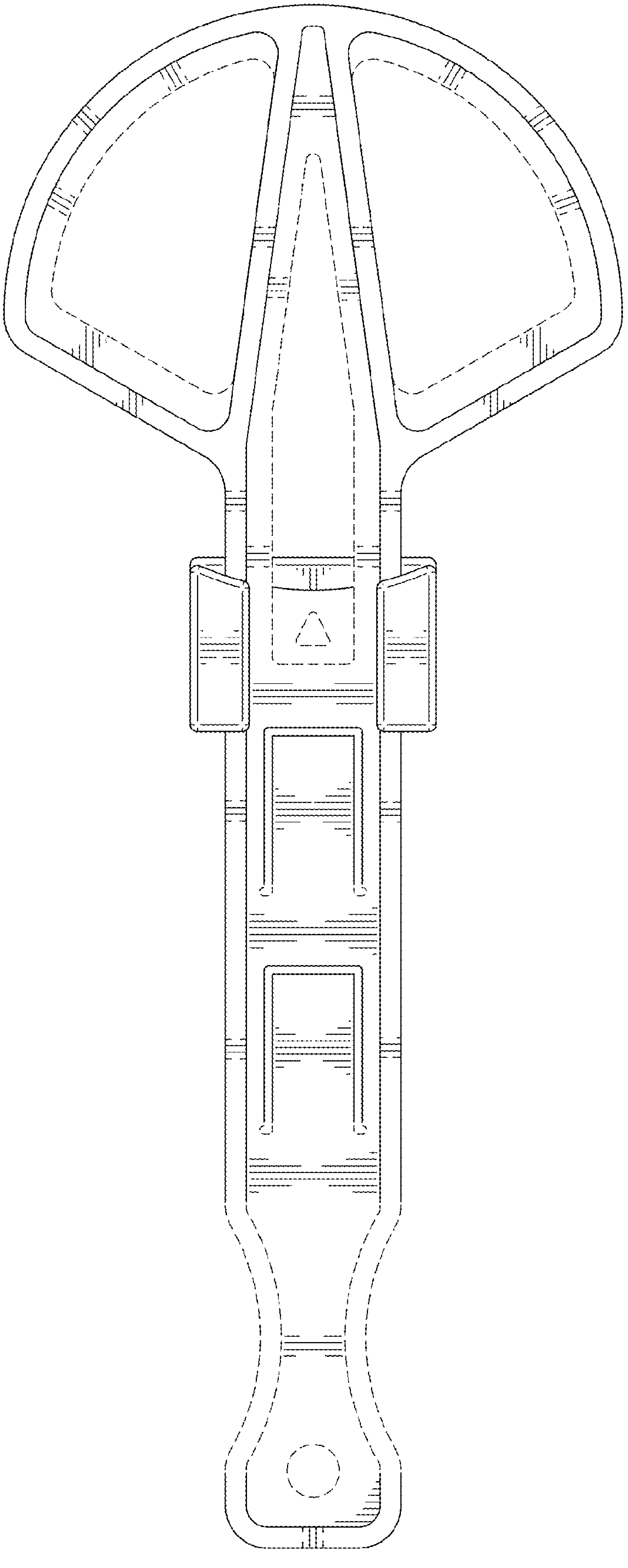

FIG. 7

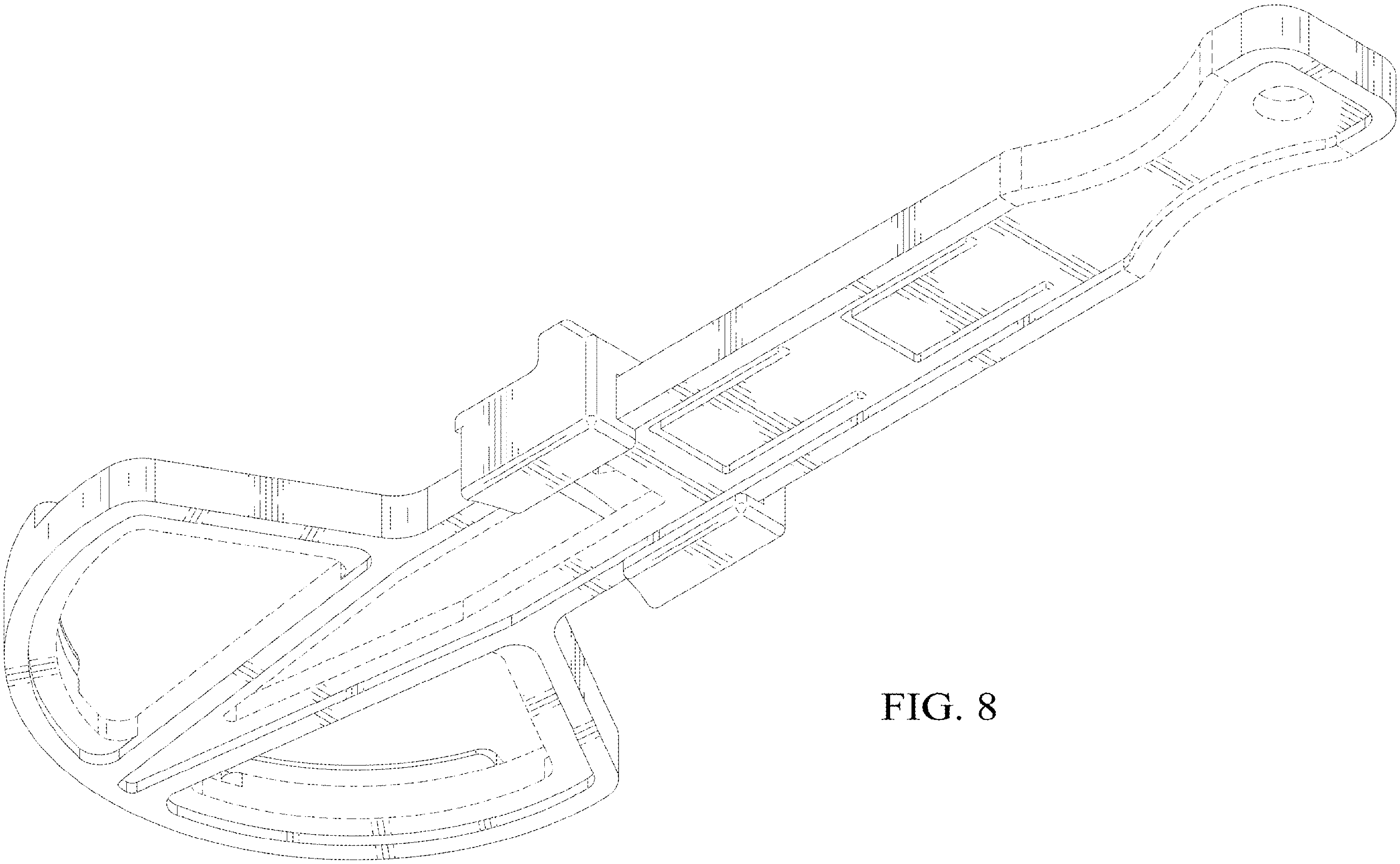

FIG. 8

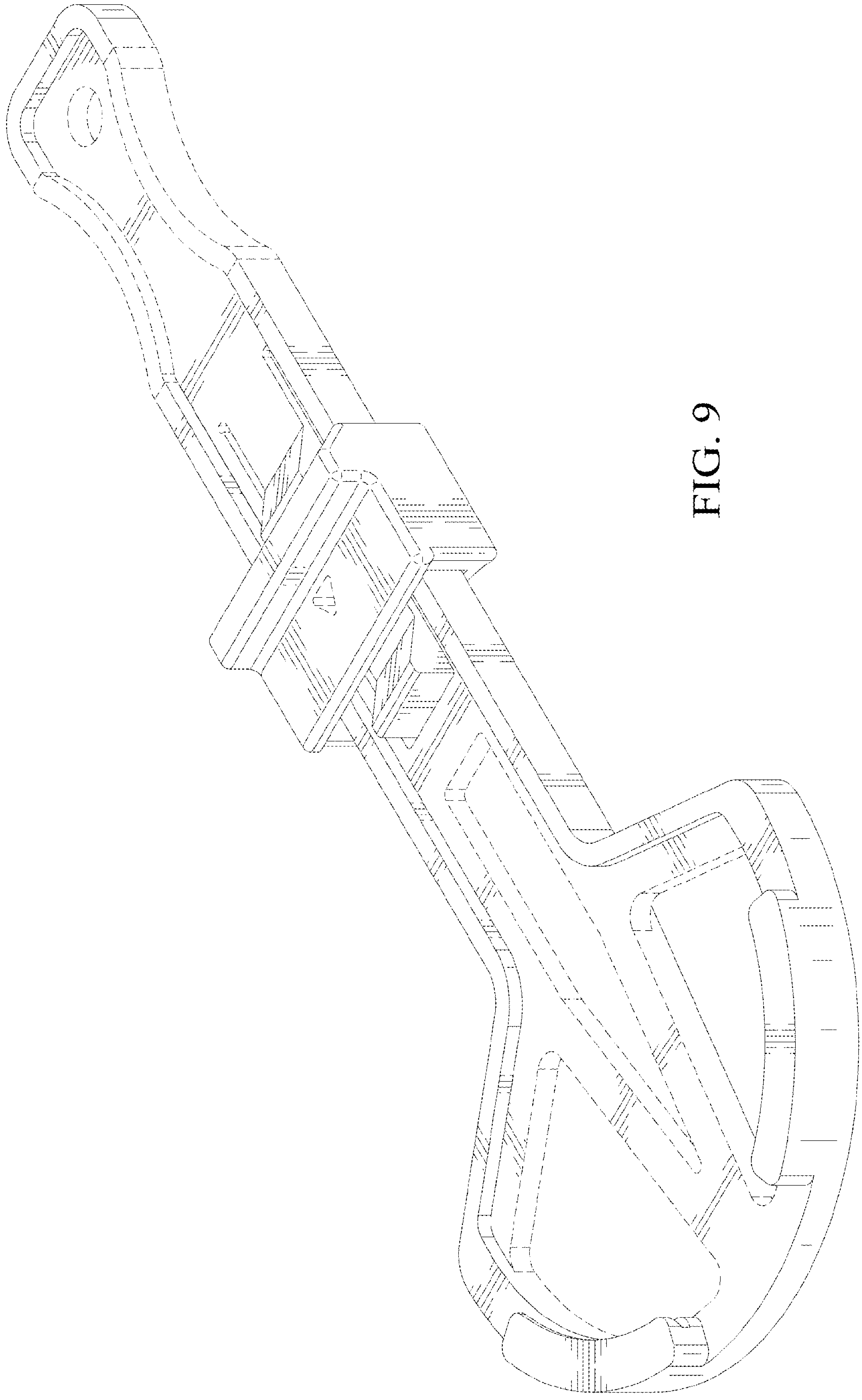

FIG. 9

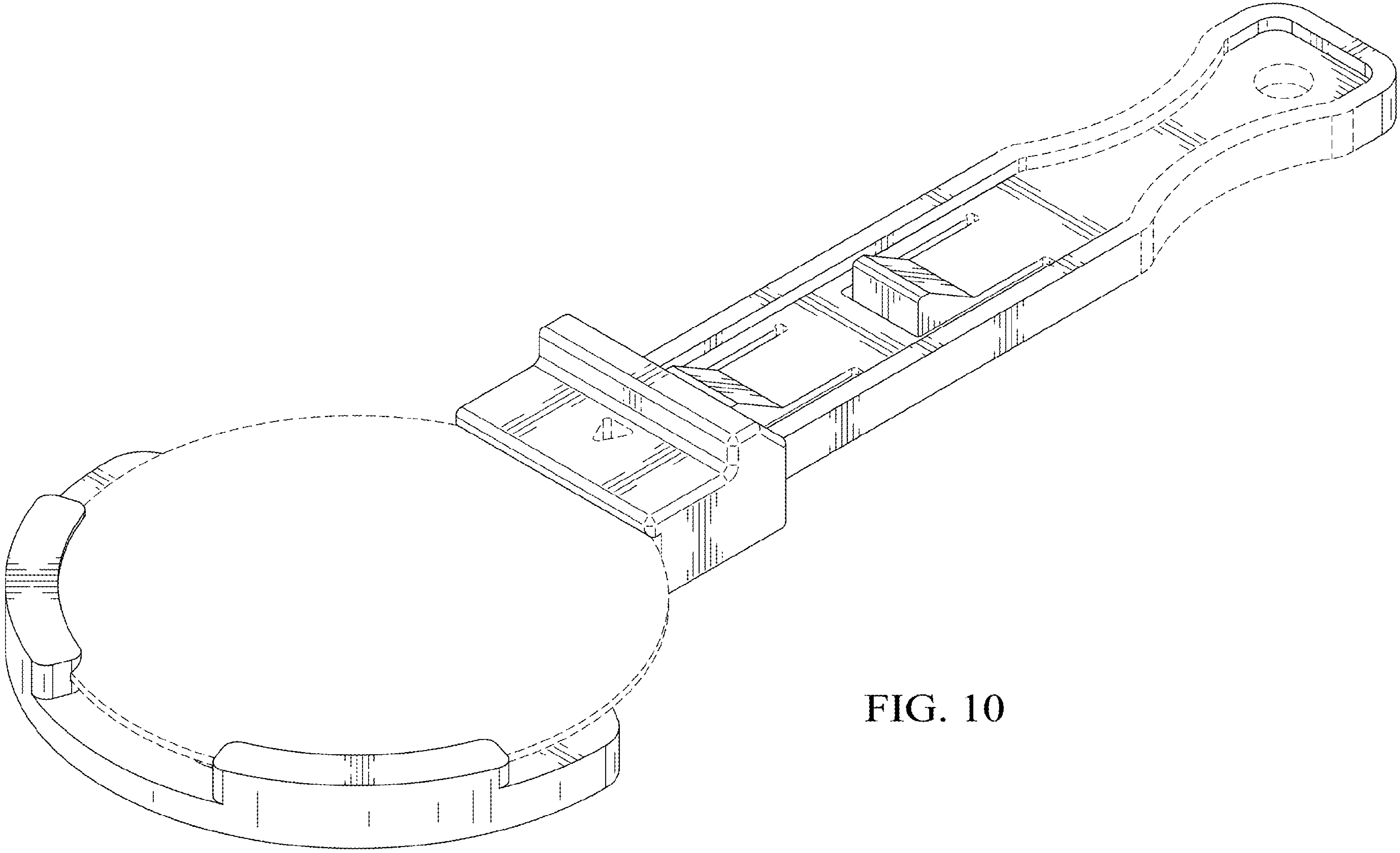

FIG. 10